1. General description

Planar Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD882D (DFN1006D-2) leadless ultra small Surface-Mounted Device (SMD) plastic package with visible and solderable side pads.

2. Features and benefits

- Average forward current: I_{F(AV)} ≤ 0.2 A
- Reverse voltage: V_R ≤ 60 V
- Low forward voltage: V_F ≤ 600 mV
- · Solderable side pads
- Package height typ. 0.37 mm
- Qualified according to AEC-Q101 and recommended for use in automotive applications

3. Applications

- · LED backlight for mobile application
- Low voltage rectification
- · High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Low power consumption applications

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
I _{F(AV)}	average forward current	δ = 0.5; f = 20 kHz; square wave; T _{amb} \leq 130 °C	[1]	-	-	0.2	А
		δ = 0.5; f = 20 kHz; square wave; T _{sp} \leq 140 °C		-	-	0.2	А
V _R	reverse voltage	T _j = 25 °C		-	-	60	V
V _F	forward voltage	I_F = 200 mA; pulsed; $t_p \le 300$ μs; $\delta \le 0.02$; T_j = 25 °C		-	540	600	mV
I _R	reverse current	V_R = 10 V; pulsed; $t_p \le 2$ ms; $\delta \le 0.02$; T_j = 25 °C		-	2	10	μΑ

[1] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.



5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]		
2	A	anode	Transparent top view DFN1006D-2 (SOD882D)	K 【 A sym001

[1] The marking bar indicates the cathode.

6. Ordering information

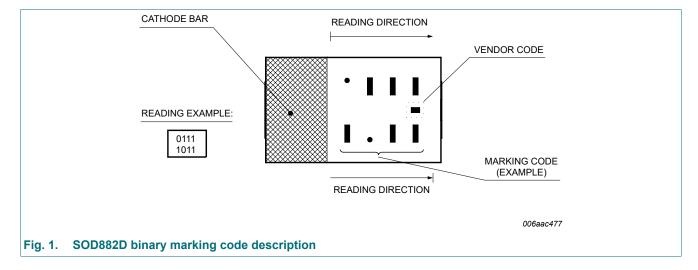
Table 3. Ordering information

Type number	Package					
	Name	Description	Version			
PMEG6002ELD-Q	DFN1006D-2	leadless ultra small plastic package with side-wettable flanks (SWF); 2 terminals; 0.65 mm pitch; 1 mm x 0.6 mm x 0.4 mm body	SOD882D			

7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG6002ELD-Q	1111
	1010



8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V _R	reverse voltage	T _j = 25 °C		-	60	V
I _F	forward current	T _{sp} ≤ 140 °C		-	0.28	А
I _{F(AV)}	average forward current	δ = 0.5; f = 20 kHz; square wave; $T_{amb} \le$ 130 °C	[1]	-	0.2	А
		δ = 0.5; f = 20 kHz; square wave; $T_{sp} \le$ 140 °C		-	0.2	А
I _{FRM}	repetitive peak forward current	$t_p \le 1 \text{ ms}; \delta \le 0.25$		-	1	А
I _{FSM}	non-repetitive peak forward current	t _p = 8 ms; square wave; T _{j(init)} = 25 °C		-	3	А
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	[2]	-	370	mW
			[3]	-	735	mW
			[1]	-	1090	mW
Tj	junction temperature			-	150	°C
T _{amb}	ambient temperature			-55	150	°C
T _{stg}	storage temperature			-65	150	°C

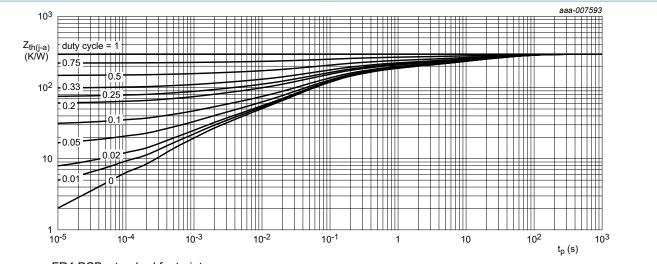
- [1] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.
- [2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.
- 3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

9. Thermal characteristics

Table 6. Thermal characteristics

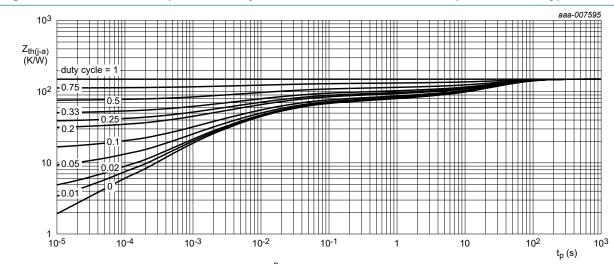
Symbol	Parameter	Conditions		Min	Тур	Max	Unit
"'(J-a)	thermal resistance from junction to ambient]	[1] [2]	-	-	340	K/W
			[1] [3]	-	-	170	K/W
			[1] [4]	-	-	115	K/W
R _{th(j-sp)}	thermal resistance from junction to solder point		[5]	-	-	20	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [4] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.
- [5] Soldering point of cathode tab.



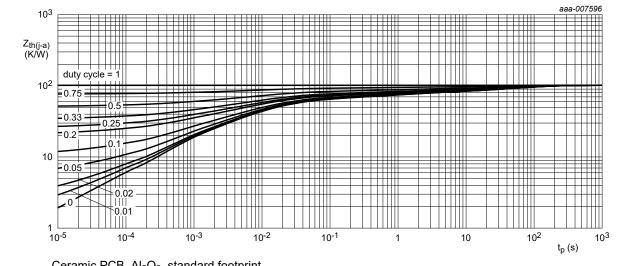
FR4 PCB, standard footprint

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm²

Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



Ceramic PCB, Al₂O₃, standard footprint

Transient thermal impedance from junction to ambient as a function of pulse duration; typical values Fig. 4.

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _F	forward voltage	I_F = 0.1 mA; pulsed; $t_p \le 300$ μs; $δ \le 0.02$; T_j = 25 °C	-	130	170	mV
		I_F = 1 mA; pulsed; $t_p \le 300$ μs; $δ \le 0.02$; T_j = 25 °C	-	190	230	mV
		I_F = 10 mA; pulsed; $t_p \le 300$ μs; $δ \le 0.02$; T_j = 25 °C	-	260	300	mV
		I_F = 100 mA; pulsed; $t_p \le 300$ μs; $δ \le 0.02$; T_j = 25 °C	-	410	470	mV
		I_F = 200 mA; pulsed; $t_p \le 300$ μs; $δ \le 0.02$; T_j = 25 °C	-	540	600	mV
I _R	reverse current	V_R = 10 V; pulsed; $t_p \le 2$ ms; $\delta \le 0.02$; T_j = 25 °C	-	2	10	μΑ
		V_R = 60 V; pulsed; $t_p \le 2$ ms; $\delta \le 0.02$; T_j = 25 °C	-	20	100	μΑ
		V_R = 10 V; pulsed; $t_p \le 300 \mu s$; $\delta \le 0.02$; T_{amb} = 100 °C	-	310	-	μΑ
		V_R = 60 V; pulsed; $t_p \le 300 \mu s$; $\delta \le 0.02$; T_{amb} = 100 °C	-	2	-	mA
C _d	diode capacitance	V _R = 1 V; f = 1 MHz; T _j = 25 °C	-	15	20	pF
t _{rr}	reverse recovery time	I_F = 10 mA; I_R = 10 mA; $I_{R(meas)}$ = 1 mA; I_L = 100 Ω; I_j = 25 °C	-	4.5	-	ns

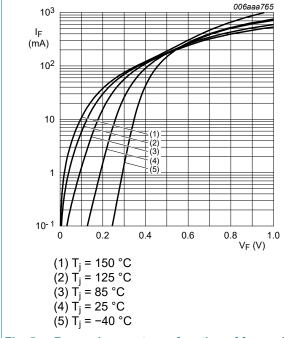
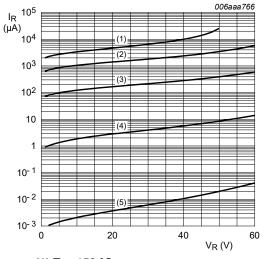


Fig. 5. Forward current as a function of forward voltage; typical values



- (1) $T_j = 150 \, ^{\circ}C$
- (2) $T_j = 125 \,^{\circ}\text{C}$ (3) $T_j = 85 \,^{\circ}\text{C}$ (4) $T_j = 25 \,^{\circ}\text{C}$ (5) $T_j = -40 \,^{\circ}\text{C}$

Fig. 6. Reverse current as a function of reverse voltage; typical values

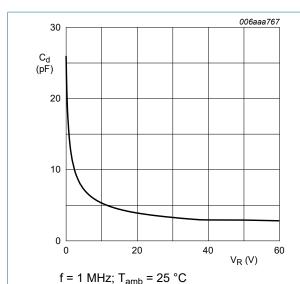
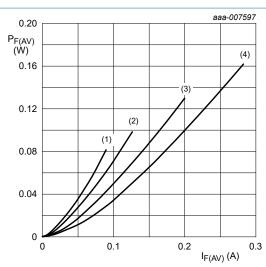
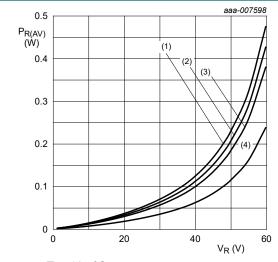


Fig. 7. Diode capacitance as a function of reverse voltage; typical values



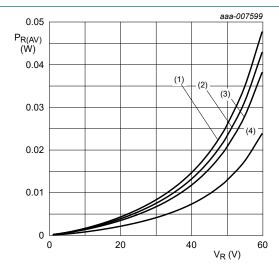
$$\begin{split} &T_j = 150 \text{ °C} \\ &(1) \ \delta = 0.1; \ f = 20 \text{ kHz} \\ &(2) \ \delta = 0.2; \ f = 20 \text{ kHz} \\ &(3) \ \delta = 0.5; \ f = 20 \text{ kHz} \\ &(4) \ \delta = 1 \ (DC) \end{split}$$

Fig. 8. Average forward power dissipation as a function of average forward current; typical values



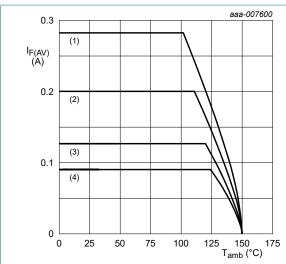
 $T_j = 125$ °C (1) $\delta = 1$ (DC) (2) $\delta = 0.9$; f = 20 kHz (3) $\delta = 0.8$; f = 20 kHz (4) $\delta = 0.5$; f = 20 kHz

Fig. 9. Average reverse power dissipation as a function of reverse voltage; typical values



 $T_j = 85 \,^{\circ}\text{C}$ (1) $\delta = 1 \,(\text{DC})$ (2) $\delta = 0.9$; $f = 20 \,\text{kHz}$ (3) $\delta = 0.8$; $f = 20 \,\text{kHz}$ (4) $\delta = 0.5$; $f = 20 \,\text{kHz}$

Fig. 10. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

T_i = 150 °C

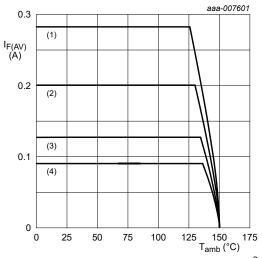
 $(1) \delta = 1 (DC)$

(2) $\delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 11. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm²

T_i = 150 °C

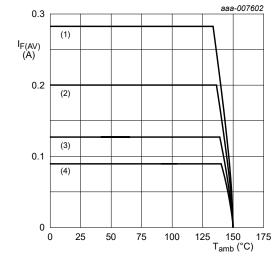
 $(1) \delta = 1 (DC)$

(2) $\delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 12. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al₂O₃, standard footprint

T_i = 150 °C

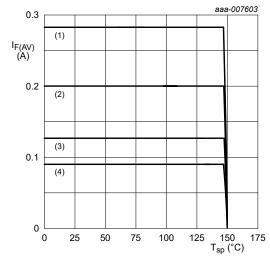
 $(1) \delta = 1 (DC)$

 $(2) \delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 13. Average forward current as a function of ambient temperature; typical values



 $T_i = 150 \,{}^{\circ}\text{C}$

 $(1) \delta = 1 (DC)$

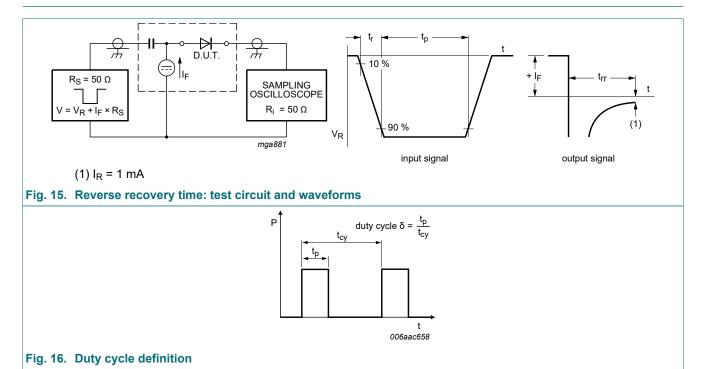
(2) δ = 0.5; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 14. Average forward current as a function of solder point temperature; typical values

11. Test information

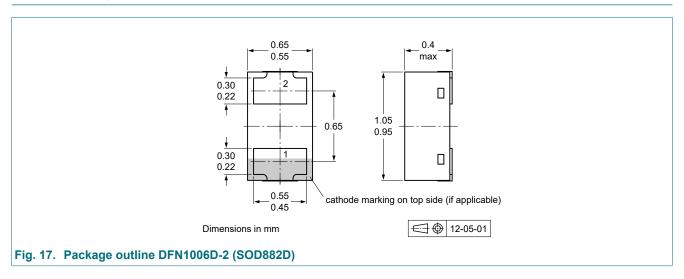


The current ratings for the typical waveforms are calculated according to the equations: $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current, $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current.

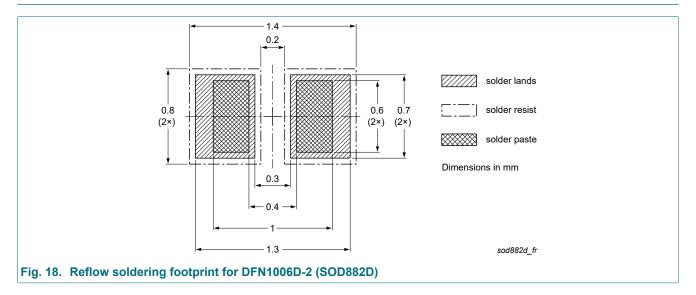
Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline



13. Soldering



14. Revision history

Table 8. Revision history

Table 6. Reviolen metery								
Data sheet ID Release date		Data sheet status	Change notice	Supersedes				
PMEG6002ELD-Q v.2	20050416	Product data sheet	-	PMEG6002ELD-Q v.1				
Modifications:	Subtitle, typo corrected: 40 V corrected to 60 V							
PMEG6002ELD-Q v.1	20240708	Product data sheet	-	-				

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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